			10-	01-2001		25
Form_PTO_1595 TRANSMITT				ION	ocket: 839.445	
10	To the Director, U.S.	Patent and Tradem			al documents or con	thereof
1.	Name of conveying party(ies		101 10 <i>ן כצווט</i>	862220 1 2. Name and address of	of receiving party(ies)	
HIDEAKI ZENKO, ICHIRO KATAOKA, SATORU WANADA AND HIDENORI SHIOTSUKA			Name: CANON KABUSHIKI KAISHA			
	Additional name(s) of conve	ying party(ies) atta	SEP 2 5 2007 ched?	Foreign Address: <u>30-2,</u>	Shimomaruko 3-chon	
3.	Nature of conveyance:			1 1	ryo, supuii	, me
	X Assignment			Domestic Address:		
	Execution Date: July 18, 200	11 and July 25, 200	1			
				City:	State	ZIP
				Additional name(s) & a	address(es) attached?	☐ Yes ⊠No
	If this document is being filed together with a new application, to A. Patent Application Number: 09/862,329 Filing Date: May 23, 2001			B. Title of Invention: SEALING COMPOSITION FOR SEALING SOLAR CELL, AND SOLAR CELL MODULE AND BUILDING MATERIAL-INTEGRAL TYPE SOLAR CELL MODULE USING SAID COMPOSITION		
	Additional numbers attached?		Yes X	No		
5.	Name and address of party to whom correspondence			6. Number of applicat	ions and patents invol	ved:
	_	oncerning document should be mailed:		One		
	Name: <u>Fitzpatri</u>	ck, Cella, Harper &	Scinto	7. Total fee (37 CFR	3.41): \$	40.00
	New York, New York 10112-3801			X Enclosed	, , , , , , , , , , , , , , , , , , , ,	
			2-3801	8. Deposit account nu	e charged to deposit a	
	Telephone No.: (212) 21	8-2100			•	,
1	Facsimile No.: (212) 21	8-2200		(Attach duplicate cor	06-1205 by of this page if paying	by deposit account):
Į	8/2001 AAHMEDI 00000065 0986 D:581	-2329 40.00 0P	DO NOT USE	THIS SPACE		
9.	Statement and signature. To the best of my knowledge copy of the original docume Elizabeth F. Holowacz Name of Person Signin	nt. Ül	ALOTT Sign	on is true and the attached when the attached at	September Da	24, 2001 te

JOINT

(AFTER APPLICATION FILED)

## ASSIGNMENT OF PATENT RIGHTS FOR THE UNITED STATES

FOR VALUE RECEIVED, WE, Hideaki ZENKO, Ichiro KATAOKA, Satoru YAMADA and Hidenori SHIOTSUKA

hereby sell, assign, transfer and convey unto CANON KABUSHIKI KAISHA

a corporation of JAPAN

having a place of business at

3-30-2, Shimomaruko, Ohta-ku, Tokyo, Japan

RECORDED: 09/25/2001

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States, in and to certain inventions relating to

SEALING COMPOSITION FOR SEALING SOLAR CELL, AND SOLAR CELL MODULE AND BUILDING MATERIAL-INTEGRAL TYPE SOLAR CELL MODULE USING SAID

and described in an application for Letters Patent of the United States filed by us on May 23, 2001 and which has been accorded Application No. 09/862329

and in and to said application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted, thereon, and all reissues and extensions thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right or priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND we hereby convenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby convenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

By: Hideaki Zenko Hideaki ZENKO	Date: July 12, 200/ July 25, 200,
Bx: Shire Salavka Ichiro KATAOKA	Date: July 18, 200/
By: Sutom Famada Satoru YAMADA	Date: July 18, 2001.
Hidenori SHIOTSUKA	Date: July (8, 200)
Ву:	Date:

PATENT REEL: 012197 FRAME: 0785